
Identification cards — Test methods —

Part 6:

Proximity cards

AMENDMENT 2: Improved RF test methods

iTeh STANDARD PREVIEW

*Cartes d'identification — Méthodes d'essai —
(standards.iteh.ai)
Partie 6: Cartes de proximité*

AMENDEMENT 2: Méthodes d'essai RF améliorées

<https://standards.iteh.ai/catalog/standards/sist/91209b6f-843a-4157-89d8-f753b5c6d4b7/iso-iec-10373-6-2001/Amd.2:2003>

PDF disclaimer

This PDF file may contain embedded typefaces. In accordance with Adobe's licensing policy, this file may be printed or viewed but shall not be edited unless the typefaces which are embedded are licensed to and installed on the computer performing the editing. In downloading this file, parties accept therein the responsibility of not infringing Adobe's licensing policy. The ISO Central Secretariat accepts no liability in this area.

Adobe is a trademark of Adobe Systems Incorporated.

Details of the software products used to create this PDF file can be found in the General Info relative to the file; the PDF-creation parameters were optimized for printing. Every care has been taken to ensure that the file is suitable for use by ISO member bodies. In the unlikely event that a problem relating to it is found, please inform the Central Secretariat at the address given below.

iTeh STANDARD PREVIEW
(standards.iteh.ai)

[ISO/IEC 10373-6:2001/Amd 2:2003](https://standards.iteh.ai/catalog/standards/sist/91209b6f-843a-4157-89d8-f753b5c6d4b7/iso-iec-10373-6-2001-amd-2-2003)

<https://standards.iteh.ai/catalog/standards/sist/91209b6f-843a-4157-89d8-f753b5c6d4b7/iso-iec-10373-6-2001-amd-2-2003>

© ISO/IEC 2003

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either ISO at the address below or ISO's member body in the country of the requester.

ISO copyright office
Case postale 56 • CH-1211 Geneva 20
Tel. + 41 22 749 01 11
Fax + 41 22 749 09 47
E-mail copyright@iso.org
Web www.iso.org

Published in Switzerland

Foreword

ISO (the International Organization for Standardization) and IEC (the International Electrotechnical Commission) form the specialized system for worldwide standardization. National bodies that are members of ISO or IEC participate in the development of International Standards through technical committees established by the respective organization to deal with particular fields of technical activity. ISO and IEC technical committees collaborate in fields of mutual interest. Other international organizations, governmental and non-governmental, in liaison with ISO and IEC, also take part in the work. In the field of information technology, ISO and IEC have established a joint technical committee, ISO/IEC JTC 1.

International Standards are drafted in accordance with the rules given in the ISO/IEC Directives, Part 2.

The main task of the joint technical committee is to prepare International Standards. Draft International Standards adopted by the joint technical committee are circulated to national bodies for voting. Publication as an International Standard requires approval by at least 75 % of the national bodies casting a vote.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. ISO and IEC shall not be held responsible for identifying any or all such patent rights.

Amendment 2 to ISO/IEC 10373-6:2001 was prepared by Joint Technical Committee ISO/IEC JTC 1, *Information technology*, Subcommittee SC 17, *Cards and personal identification*.

ITEH STANDARD PREVIEW

(standards.iteh.ai)

[ISO/IEC 10373-6:2001/Amd 2:2003](https://standards.iteh.ai/catalog/standards/sist/91209b6f-843a-4157-89d8-f753b5c6d4b7/iso-iec-10373-6-2001-amd-2-2003)

<https://standards.iteh.ai/catalog/standards/sist/91209b6f-843a-4157-89d8-f753b5c6d4b7/iso-iec-10373-6-2001-amd-2-2003>

iTeh STANDARD PREVIEW
(standards.iteh.ai)

[ISO/IEC 10373-6:2001/Amd 2:2003](https://standards.iteh.ai/catalog/standards/sist/91209b6f-843a-4157-89d8-f753b5c6d4b7/iso-iec-10373-6-2001-amd-2-2003)

<https://standards.iteh.ai/catalog/standards/sist/91209b6f-843a-4157-89d8-f753b5c6d4b7/iso-iec-10373-6-2001-amd-2-2003>

Identification cards — Test methods —

Part 6: Proximity cards

AMENDMENT 2: Improved RF test methods

Page 2, 3.2

Add the following abbreviations and symbols:

f_{cm} Frequency of the operating field during the PICC load modulation test

H Field strength of the PCD antenna field

m Modulation index as defined in 3.3 of ISO/IEC 14443-2

t₁, *t₂* Pulse segments as defined in Figure 2 of ISO/IEC 14443-2

t_r, *t_f* Rise and fall times as defined in Figure 4 of ISO/IEC 14443-2

Page 5, 6.1.3

<https://standards.iteh.ai/catalog/standards/sist/91209b6f-843a-4157-89d8-f753b5c6d4b7/iso-iec-10373-6-2001-amd-2-2003>

Replace the 2nd note with the following:

"NOTE At 13,56 MHz the approximate inductance is 250 nH and the approximate resistance is 0,4 Ω."

Page 6, 6.1.3

Add a note after the last note:

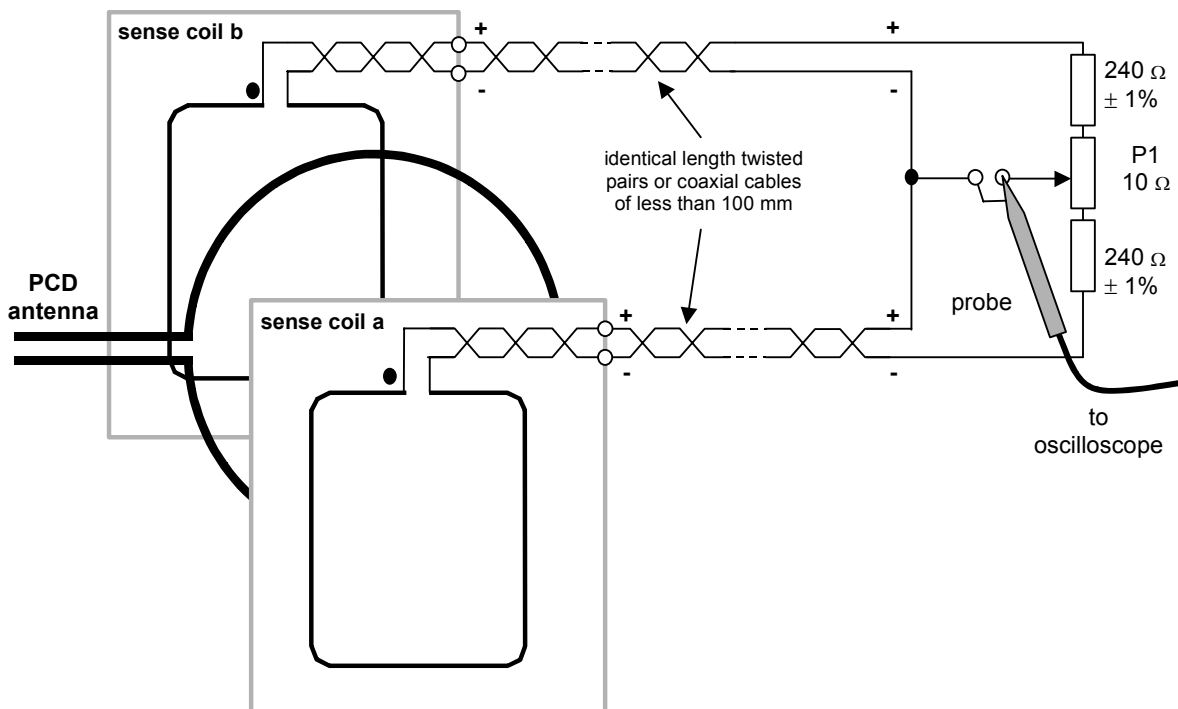
"NOTE The high impedance oscilloscope probe ground connection should be as short as possible, less than 20 mm or coaxial connection."

Page 6, 6.2

In the 4th sentence, replace the value "50 Ω" for P1 with the value "10 Ω".

Page 6, Figure 4

Replace the figure with the following:



NOTE 1 In order to avoid any unintended misalignment in case of an unsymmetrical set-up the tuning range of the potentiometer P1 is only 10 Ω. If the set-up cannot be compensated by the 10 Ω potentiometer P1 the overall symmetry of the set-up should be checked.

NOTE 2 The high impedance oscilloscope probe ground connection should be as short as possible, less than 20 mm or coaxial connection.

ISO/IEC 10373-6:2001/Amd 2:2003
<https://standards.iteh.ai/catalog/standards/sist/843a-4157-89d8-f753b5c6d4b7/iso-iec-10373-6-2001-amd-2-2003>
Figure 4 — Test set-up (principle)

Page 7, 6.2.3

Add the following sentence after the first sentence:

“The dimensional tolerance shall be better than ± 0,5 mm.”

Pages 8 and 9, Clause 7

Replace 7.1, 7.2 and 7.3 with the following:

7.1 PICC load modulation amplitude

7.1.1 Purpose

The purpose of this test is to determine the amplitude of the PICC load modulation signal within the operating field range [H_{min} , H_{max}] as specified in the base standard. Also the functionality of the PICC for Type A and Type B within their corresponding modulation ranges as defined in the base standard shall be determined.

7.1.2 Test procedure

Step 1: The load modulation test circuit of Figure 4 and the Test PCD assembly of Figure 5 are used.

Adjust the RF power delivered by the signal generator to the test PCD antenna to the required field strength as measured by the calibration coil. Connect the output of the load modulation test circuit of Figure 4 to a digital sampling oscilloscope. The $10\ \Omega$ potentiometer P1 shall be trimmed to minimise the residual carrier. This signal shall be at least 40 dB lower than the signal obtained by shorting one sense coil.

Step 2: The PICC under test shall be placed in the DUT position, concentric with sense coil a. The RF drive into the test PCD antenna shall be re-adjusted to the required field strength.

Display a segment of at least two cycles of the waveform of the subcarrier load modulation on the digital sampling oscilloscope and store the sampled data in a file for analysis by a computer software programme (see Annex F).

NOTE 1 Care should be taken to apply a proper synchronization method for low amplitude load modulation.

Fourier transform exactly two subcarrier cycles of the sampled modulation waveform using suitable computer software. Use a discrete Fourier transformation with a scaling such that a pure sinusoidal signal results in its peak magnitude. In order to minimize transient effects, avoid to analyse a subcarrier cycle immediately following a non-modulating period or a phase shift of the subcarrier.

The resulting peak amplitudes of the upper and lower sidebands at $f_c + f_s$ and $f_c - f_s$ shall be above the value defined in the base standard.

A REQA or a REQB command sequence as defined in ISO/IEC 14443-3 shall be sent by the Test PCD to obtain a signal or load modulation response from the PICC.

The frequency f_{cm} of the carrier delivered by the signal generator to the test PCD antenna shall be such that two subcarrier cycles correspond exactly to an integer number of samples. The frequency which fulfils this requirement (with common oscilloscope sampling rates) and which is the closest to the nominal carrier frequency f_c defined in ISO/IEC 14443-2 is $f_{cm} = 13,559322$ MHz.

The discrete Fourier transformation shall be done at the exact sidebands frequencies generated by the PICC under test, i.e. $f_{cm}(1 - f_s/f_c)$ and $f_{cm}(1 + f_s/f_c)$. If the programme given in Annex F is used it shall be modified to replace 13,56 MHz by the exact value of f_{cm} during the test.

NOTE 2 In order to limit the worst case measurement error to approximately 5 % due to inexact frequencies the following tolerances apply:

- $f_{cm} = 13,559322$ MHz, with a relative tolerance of $\pm 50 \times 10^{-6}$
- f_{cm} measurement relative error + oscilloscope sampling rate relative error: $\pm 10 \times 10^{-6}$

(The oscilloscope sampling rate error may be compensated if the f_{cm} measurement is done by the digital sampling oscilloscope. A better than $\pm 10 \times 10^{-6}$ relative uncertainty may be achieved by sampling more than 500 periods of unmodulated carrier and using interpolation to know precisely the time of the first and of the last rising edge of the carrier.)

NOTE 3 In order to limit the measurement error due to noise (quantization noise, PICC noise...) the following techniques may be used:

- increasing the oscilloscope sampling rate;
- increasing the number of subcarrier cycles used in the Fourier transformation.

NOTE 4 For type B PICC load modulation test, the oscilloscope FFT option may also be used on a large number of subcarrier cycles with neither transient effect nor phase shift (i.e. on a stable part of synchronization time TR1 as defined in ISO/IEC 14443-2:2001, 9.2.5, or on a stable part of SOF as defined in ISO/IEC 14443-3:2001, 7.1.4).

7.1.3 Test report

The test report shall give the measured peak amplitudes of the upper and lower sidebands at $f_c + f_s$ and $f_c - f_s$ and the applied fields and modulations.

7.2 PICC reception

7.2.1 Purpose

The purpose of this test is to verify the ability of the PICC to receive the PCD message under the specified conditions given in Tables 1 and 2.

7.2.2 Conditions for type A

Table 1 defines the additional test conditions to be applied for type A.

Table 1 — Additional test conditions for type A

Condition	<i>H</i> A/m	<i>t1</i> µs	<i>t2</i> µs
1	1,5	3	0,5
2	1,5	2	0,7
3	4,5	3	0,5
4	4,5	2	0,7
5	7,5	3	0,5
6	7,5	2	0,7

iTeh STANDARD PREVIEW
(standards.iteh.ai)

7.2.2.1 Test procedure

Under the conditions defined in Table 1 the PICC shall answer to a REQA with ATQA.

7.2.2.2 Test report

<https://standards.iteh.ai/catalog/standards/sist/91209b6f-843a-4157-89d8-f753b5c6d4b7/iso-iec-10373-6-2001-amd-2-2003>

The test report shall confirm the intended operation under the conditions defined in Table 1.

7.2.3 Conditions for type B

Table 2 defines the additional test conditions to be applied for type B.

Table 2 — Additional test conditions for type B

Condition	H A/m	m %	t_r μs	t_f μs
1	1,5	8	1	1
2	1,5	8	2	2
3	1,5	14	1	1
4	1,5	14	2	2
5	4,5	8	1	1
6	4,5	8	2	2
7	4,5	14	1	1
8	4,5	14	2	2
9	7,5	8	1	1
10	7,5	8	2	2
11	7,5	14	1	1
12	7,5	14	2	2

7.2.3.1 Test procedure

Under the conditions defined in Table 2 the PICC shall answer to a REQB with ATQB.

7.2.3.2 Test report

The test report shall confirm the intended operation under the conditions defined in Table 2.

7.3 PICC resonance frequency (informative)

7.3.1 Purpose

The test may be used to measure the resonance frequency of a PICC.

When two or more PICCs are placed in the same PCD energizing field, the resonance frequency of each PICC decreases.

Care should be taken in designing each PICC resonance frequency.

7.3.2 Procedure

The resonance frequency of a PICC is measured by using an impedance analyser or a LCR-meter connected to a calibration coil. The coil of the PICC should be placed on the calibration coil as close as possible, with the axes of the two coils being congruent. The resonance frequency is that frequency at which the resistive part of the measured complex impedance is at maximum.

7.3.3 Test report

The test report shall give the PICC resonance frequency and the measurement conditions.